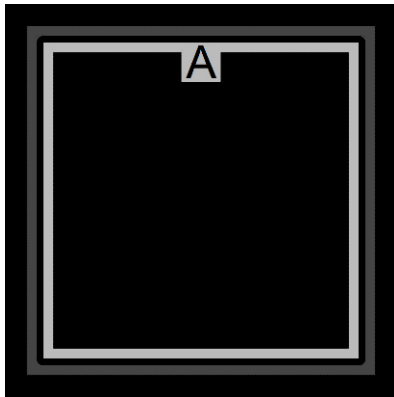


Silicon PIN Photodiode



DESCRIPTION

T1170P is pin photodiode chip with 0.88 mm² sensitive area detecting visible and near infrared radiation. Anode is the bond pad on top.

GENERAL INFORMATION

The datasheet is based on Vishay optoelectronics sample testing under certain predetermined and assumed conditions, and is provided for illustration purpose only. Customers are encouraged to perform testing in actual proposed packaged and used conditions. Vishay optoelectronics die products are tested using Vishay optoelectronics based quality assurance procedures and are manufactured using Vishay optoelectronics established processes. Estimates such as those described and set forth in this datasheet for semiconductor die will vary depending on a number of packaging, handling, use, and other factors. Therefore sold die may not perform on an equivalent basis to standard package products.

FEATURES

- Package type: chip
- Package form: single chip
- Dimensions (L x W x H in mm): 1.17 x 1.17 x 0.28
- Radiant sensitive area (in mm²): 0.88
- Peak sensitivity wavelength: 920 nm
- High photo sensitivity
- Suitable for visible light and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\phi = \pm 60^\circ$
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- High speed photo detector

PRODUCT SUMMARY

COMPONENT	I_{ra} (μA)	ϕ (deg)	$\lambda_{0.5}$ (nm)
T1170P	7	± 60	600 to 1040

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
T1170P-SD-F	wafer sawn on foil with disco frame	MOQ: 23 500 pcs	chip

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ C$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	60	V
Junction temperature		T_j	100	$^\circ C$
Operating temperature range		T_{amb}	-40 to +100	$^\circ C$
Storage temperature range		T_{stg1}	-40 to +100	$^\circ C$
Storage temperature range on foil		T_{stg2}	-40 to +50	$^\circ C$

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Breakdown voltage	$I_R = 100\text{ }\mu\text{A}$, $E = 0$	$V_{(BR)}$	60			V
Reverse dark current	$V_R = 10\text{ V}$, $E = 0$	I_{ro}		< 1	3	nA
Diode capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D		12		pF
	$V_R = 3\text{ V}$, $f = 1\text{ MHz}$, $E = 0$	C_D		4		pF
Reverse light current	$E_e = 1\text{ mW/cm}^2$, $\lambda = 950\text{ nm}$, $V_R = 5\text{ V}$	I_{ra}		7		μA
Angle of half sensitivity		φ		± 60		deg
Wavelength of peak sensitivity		λ_p		920		nm
Range of spectral bandwidth		$\lambda_{0.5}$		600 to 1040		nm
Rise time	$V_R = 10\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 830\text{ nm}$	t_r		100		ns
Fall time	$V_R = 10\text{ V}$, $R_L = 1\text{ k}\Omega$, $\lambda = 830\text{ nm}$	t_f		100		ns

Notes

- The measurements are based on samples which are mounted on TO18-header without epoxy coating

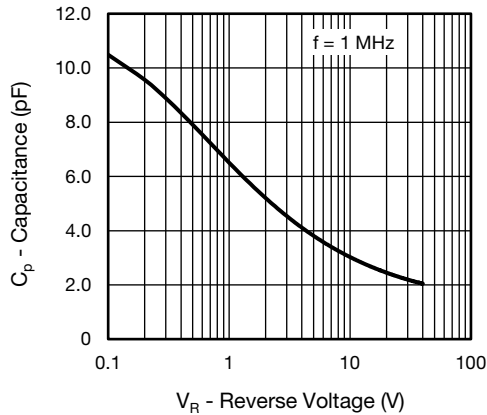
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 1 - Diode Capacitance vs. Reverse Voltage

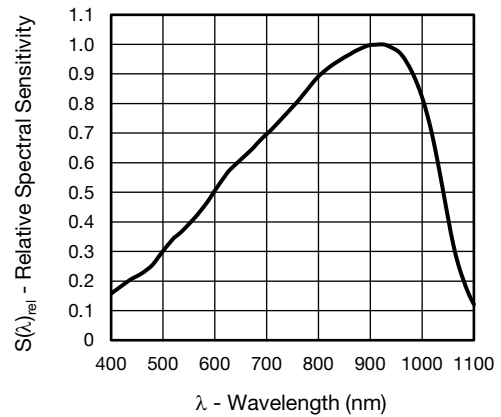
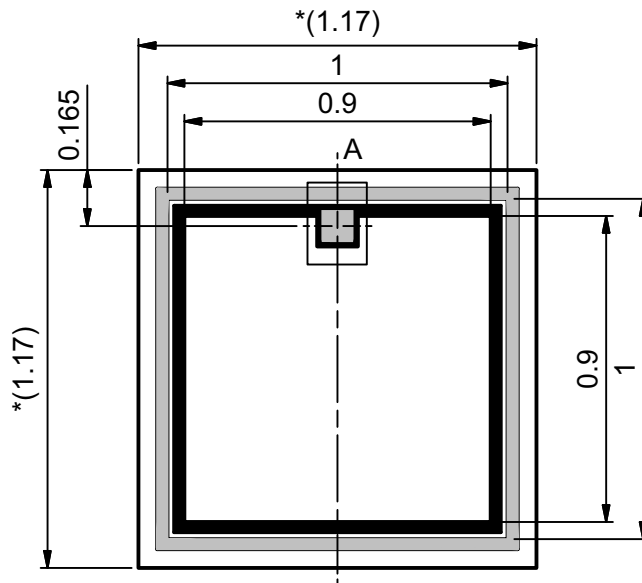
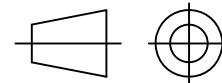
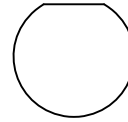


Fig. 2 - Relative Spectral Sensitivity vs. Wavelength without Epoxy Coating

DIMENSIONS in millimeters


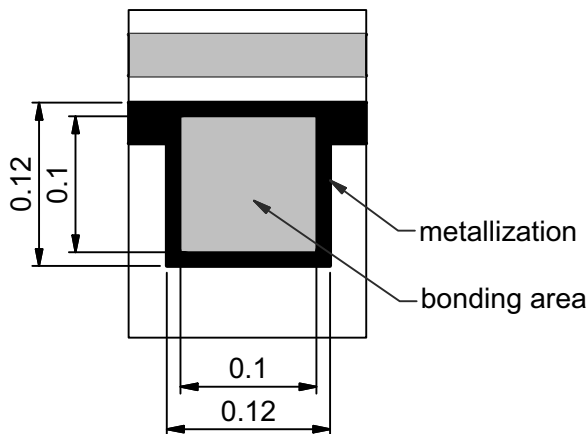
Orientation of wafer flat



Technical drawings according to DIN specification.

*only for information:
dimension of sawn die under consideration of 30 μm saw kerf

A (200:1)


 Dimensions in mm
Not indicated tolerances ± 0.005

 Opt. sensitive area: 0.88 mm²

 Bonding area: 100 μm x 100 μm
Bonding restricted to this area
in order to avoid damage
of adjacent structures

 Thickness: 280 μm \pm 15 μm

 Drawing-No.: 9.000-5134.01-4
Issue: 1; 25.04.2014

MECHANICAL DIMENSIONS					
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Length of chip edge (x-direction)	L_x		1.17		mm
Length of chip edge (y-direction)	L_y		1.17		mm
Sensitive area	A_S		0.88		mm ²
Wafer diameter	D		100		mm
Die height	H	0.265	0.28	0.295	mm
Bond pad anode			0.1 x 0.1		mm ²



ADDITIONAL INFORMATION	
Frontside metallization, anode	Al
Backside metallization, cathode	NiV-Ag
Dicing	sawing
Die bonding technology	epoxy bonding

Note

- All chips are checked in accordance with the Vishay Semiconductor, specification of visual inspection FVOV6870. The visual inspection shall be made in accordance with the "specification of visual inspection as referenced". The visual inspection of chip backside is performed with stereo microscope with incident light and 40x to 80x magnification. The quality inspection (final visual inspection) is performed by production. An additional visual inspection step as special release procedure by QM is not installed.

HANDLING AND STORAGE CONDITIONS

- The hermetically sealed shipment lots shall be opened in temperature and moisture controlled cleanroom environment only. It is mandatory to follow the rules for disposition of material that can be hazardous for humans and environment.
- Product must be handled only at ESD safe workstations. Standard ESD precautions and safe work environments are as defined in MIL-HDBK-263.
- Singulated die are not to be handled with tweezers. A vacuum wand with non metallic ESD protected tip should be used.

PACKING

Chips are fixed on adhesive foil. Upon request the foils can be mounted on plastic frame or disco frame. For shipment, the wafers are arranged to stacks and hermetically sealed in plastic bags to ensure protection against environmental influence (humidity and contamination).

Use for recycling reliable operators only. We can help getting in touch with your nearest sales office. By agreement we will take back packing material, if it is sorted. You will have to bear the costs of transport. We will invoice you for any costs incurred for packing material that is returned unsorted or which we are not obliged to accept.



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